

MATERIAL DECLARATION SHEET

Material Number	CRM1206 Series (less than 1Ω)			
Product Line	High power lead free chip resistors			
Compliance Date	09/01/2016			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	8.588	Aluminum oxide	1344-28-1	96	81.946	85.360
				Silicon dioxide	14808-60-7	2	1.707	
				Magnesium oxide	1309-48-4	2	1.707	
2	Top conductor	Silver	0.162	Silver	7440-22-4	100	1.610	1.610
3	Bottom conductor	Silver	0.0543	Silver	7440-22-4	100	0.540	0.540
4	Resistor	Ruthenium Oxide	0.1087	Palladium	7440-05-3	40	0.432	1.080
				Silver	7440-22-4	35	0.378	
				Ruthenium(IV) oxide	12036-10-1	15	0.162	
5	First encapsulating	Glass	0.1038	Silicon dioxide	14808-60-7	10	0.108	1.032
				Glass	65997-17-3	92	0.949	
6	Overcoat	Resin	0.2327	Chromium(III) oxide	1308-38-9	8	0.083	2.313
				Resin	25036-25-3	100	2.313	
7	Side conductor	Silver	0.2341	Silver	7440-22-4	85	1.978	2.327
				Resin	9003-36-5	15	0.349	
8	Plating (Middle)	Nickel	0.1985	Nickel	7440-02-0	100	1.973	1.973
9	Plating (Outer)	Tin	0.3573	Tin	7440-31-5	100	3.551	3.551
10	Marking	Resin	0.0215	Resin	29690-82-2	70	0.150	0.214
				Titanium(IV) oxide	1317-80-2	30	0.064	
Total weight			10.0609					

This Document was updated on: 12/24/2019

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.